High Performance and Cost Effective ENIG | 高性能低操作成本化学镍金技术

As a market leader, Dow Electronic Materials special formulated DURAPOSIT™ SMT-88 Electroless Nickel and AUROLECTROLESS™ SMT520 Immersion Gold which brings proven production performances, low cost of ownership to our customers and partners in print circuit board industry.

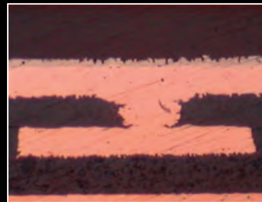
陶氏电子材料身为业界领导者，我们特别开发的DURAPOSIT™ SMT-88 化学镍及AUROLECTROLESS™ SMT520 浸金产品，为印刷线路板的客户和合作伙伴提供可靠及高性价比的解决方桉。

DURAPOSIT™ SMT-88 化学镍

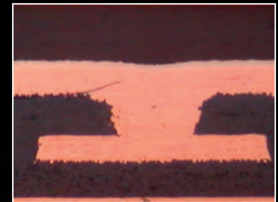
Advantages 优点

- Elimination of Black Pad and skip plating
  降低“镍黑垫”及 漏镀风险
- Excellent solderability for tin-lead and lead-free solder joint
  对于锡铅与无铅焊料具有优异的焊锡性

Old ENIG System



New ENIG System



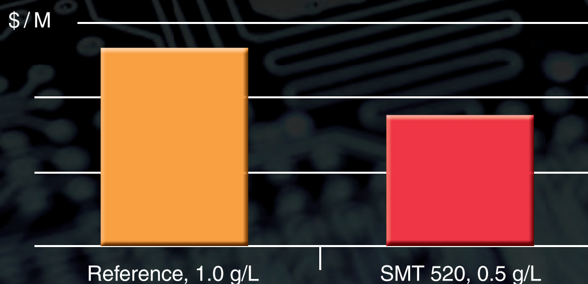
High performance E'less Ni and low gold porosity to improve Ni corrosion under multi-OSP passes

AUROLECTROLESS™ SMT520 浸金

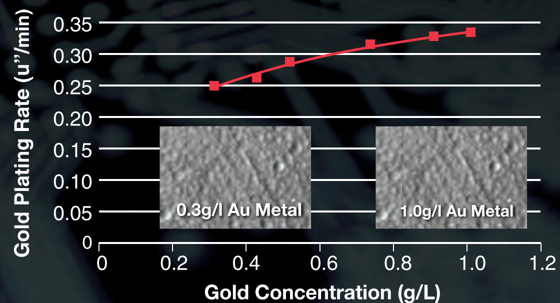
Advantages 优点

- Low gold content operation to save running cost
  低金盐浓度操作(0.5–0.6 g/Lt)可降低金盐成本
- No significant performance effect under dry film leaching condition
  对乾膜有机物析出不敏感可用于选择性化镍金製程
- Dense Au deposition with low porosity to minimize Ni corrosion risk after multi-OSP post-treatment
  沉金结构緻密，低疏孔性，可降低多次OSP后处理镍腐蚀风险

Cost Saving of Gold Consumption
(30% gold salt reduction)



Effect of Gold Concentration



Electronic Materials

®™ Trademarks of The Dow Chemical Company (“Dow”) or an affiliated company of Dow